

AMENDMENT TO THE SPECIFICATION

Please replace paragraph [0001] with the following:

[0001] This application is a continuation-in-part of Serial No. 10/067,833, filed February 8, 2002, [[allowed]] issued as U.S. Pat. No. 6,692,619, which claims priority from Provisional Application Serial No. 60/312,329 filed August 14, 2001, entitled “Method for Making Composite Soft Magnetic Films,” the entire disclosures of which are hereby incorporated herein by reference.

Please replace paragraph [0044] with the following:

[0044] The pie-shaped and ring-shaped targets of Figures 3 and 4 are suitable for magnetron sputtering of magnetically soft materials. The targets with pie-shaped sectors require that two kinds of sectors have similar saturation magnetization. The targets with nested ring-shaped sectors need at least three separated power supplies for firing the targets. The embodiment with sintered targets discloses another approach under the disclosed concept of decomposition in U.S. Serial No. 10/067,833, issued as U.S. Pat. No. 6,692,619, but does not require the similarity of saturation magnetization of these two kinds of sectors and at least three separated power supplies.